



# 128Kx8 MONOLITHIC SRAM PRELIMINARY\*

## FEATURES

- Access Times 17, 20, 25, 35, 45, 55nS
- Radiation Tolerant Devices Available
- Packaging
  - 36 pin Ceramic Flat Pack, JEDEC Approved Revolutionary Pinout (Package 200)
  - 36 pin Ceramic SOJ, JEDEC Approved Revolutionary Pinout (Package 100)
  - 32 pin Ceramic DIP, JEDEC Approved Pinout (Package 300)

- MIL-STD-883 Compliant Devices Available
- Commercial, Industrial and Military Temperature Range
- 5 Volt Power Supply
- Low Power CMOS
- TTL Compatible Inputs and Outputs

*\* This data sheet describes a product not fully characterized and is subject to change*

### FIG. 1 PIN CONFIGURATION FOR WMS128K8-XFX

TOP VIEW  
FLAT PACK

NC	1	36	NC
A0	2	35	A16
A1	3	34	A15
A2	4	33	A14
A3	5	32	A13
CS	6	31	OE
IO0	7	30	IO7
IO1	8	29	IO6
V <sub>cc</sub>	9	28	V <sub>cc</sub>
V <sub>ss</sub>	10	27	V <sub>ss</sub>
IO2	11	26	IO5
IO3	12	25	IO4
WE	13	24	A12
A4	14	23	A11
A5	15	22	A10
A6	16	21	A9
A7	17	20	A8
NC	18	19	NC

### PIN DESCRIPTION

A0-16	Address Inputs
I/O0-7	Data Input/Output
CS	Chip Select
OE	Output Enable
WE	Write Enable
V <sub>cc</sub>	+5.0V Power
V <sub>ss</sub>	Ground

### FIG. 2 PIN CONFIGURATION FOR WMS128K8-XDJX

TOP VIEW  
CSOJ

NC	1	36	NC
A0	2	35	A16
A1	3	34	A15
A2	4	33	A14
A3	5	32	A13
CS	6	31	OE
IO0	7	30	IO7
IO1	8	29	IO6
V <sub>cc</sub>	9	28	V <sub>cc</sub>
V <sub>ss</sub>	10	27	V <sub>ss</sub>
IO2	11	26	IO5
IO3	12	25	IO4
WE	13	24	A12
A4	14	23	A11
A5	15	22	A10
A6	16	21	A9
A7	17	20	A8
NC	18	19	NC

### PIN DESCRIPTION

A0-16	Address Inputs
I/O0-7	Data Input/Output
CS	Chip Select
OE	Output Enable
WE	Write Enable
V <sub>cc</sub>	+5.0V Power
V <sub>ss</sub>	Ground

### FIG. 3 PIN CONFIGURATION FOR WMS128K8-XCX

TOP VIEW  
DIP

NC	1	32	V <sub>cc</sub>
A16	2	31	A15
A14	3	30	NC
A12	4	29	WE
A7	5	28	A13
A6	6	27	A8
A5	7	26	A9
A4	8	25	A11
A3	9	24	OE
A2	10	23	A10
A1	11	22	CS
A0	12	21	IO7
IO0	13	20	IO6
IO1	14	19	IO5
IO2	15	18	IO4
V <sub>ss</sub>	16	17	IO3

### PIN DESCRIPTION

A0-16	Address Inputs
I/O0-7	Data Input/Output
CS	Chip Select
OE	Output Enable
WE	Write Enable
V <sub>cc</sub>	+5.0V Power
V <sub>ss</sub>	Ground

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**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T <sub>A</sub>	-55	+125	°C
Storage Temperature	T <sub>STG</sub>	-65	+150	°C
Signal Voltage Relative to GND	V <sub>G</sub>	-0.5	V <sub>CC</sub> +0.5	V
Junction Temperature	T <sub>J</sub>		150	°C
Supply Voltage	V <sub>CC</sub>	-0.5	7.0	V

**RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V <sub>CC</sub>	4.5	5.5	V
Input High Voltage	V <sub>IH</sub>	2.2	V <sub>CC</sub> + 0.3	V
Input Low Voltage	V <sub>IL</sub>	-0.3	+0.8	V
Operating Temp. (MIL.)	T <sub>A</sub>	-55	+125	°C

**TRUTH TABLE**

CS	OE	WE	Mode	Data I/O	Power
H	X	X	Standby	High Z	Standby
L	L	H	Read	Data Out	Active
L	X	L	Write	Data In	Active
L	H	H	Out Disable	High Z	Active

**CAPACITANCE**

(T<sub>A</sub> = +25°C)

Parameter	Symbol	Condition	Max	Unit
Input capacitance	C <sub>IN</sub>	V <sub>IN</sub> = 0V, f = 1.0MHz	20	pF
Output capacitance	C <sub>OUT</sub>	V <sub>OUT</sub> = 0V, f = 1.0MHz	20	pF

This parameter is guaranteed by design but not tested.

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**DC CHARACTERISTICS**

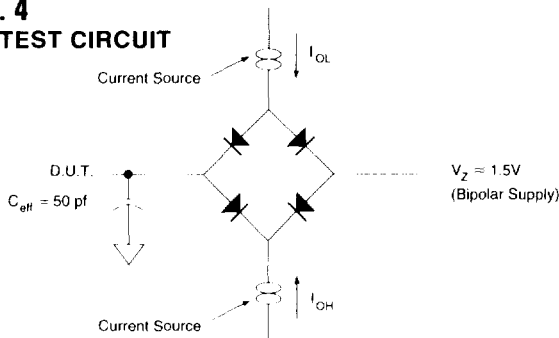
(V<sub>CC</sub> = 5.0V, V<sub>SS</sub> = 0V, T<sub>A</sub> = -55°C to +125°C)

Parameter	Sym	Conditions	-17		-20		-25		Units
			Min	Max	Min	Max	Min	Max	
Input Leakage Current	I <sub>LI</sub>	V <sub>CC</sub> = 5.5, V <sub>IN</sub> = GND to V <sub>CC</sub>		10		10		10	μA
Output Leakage Current	I <sub>LO</sub>	CS = V <sub>IH</sub> , OE = V <sub>IH</sub> , V <sub>OUT</sub> = GND to V <sub>CC</sub>		10		10		10	μA
Operating Supply Current	I <sub>CC</sub>	CS = V <sub>IL</sub> , OE = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		110		110		110	mA
Standby Current	I <sub>SB</sub>	CS = V <sub>IH</sub> , OE = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		30		30		30	mA
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 8mA, V <sub>CC</sub> = 4.5		0.4		0.4		0.4	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -4.0mA, V <sub>CC</sub> = 4.5	2.4		2.4		2.4		V

Parameter	Sym	Conditions	-35		-45		-55		Units
			Min	Max	Min	Max	Min	Max	
Input Leakage Current	I <sub>LI</sub>	V <sub>CC</sub> = 5.5, V <sub>IN</sub> = GND to V <sub>CC</sub>		10		10		10	μA
Output Leakage Current	I <sub>LO</sub>	CS = V <sub>IH</sub> , OE = V <sub>IH</sub> , V <sub>OUT</sub> = GND to V <sub>CC</sub>		10		10		10	μA
Operating Supply Current	I <sub>CC</sub>	CS = V <sub>IL</sub> , OE = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		110		70		70	mA
Standby Current	I <sub>SB</sub>	CS = V <sub>IH</sub> , OE = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		30		25		25	mA
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 8mA, V <sub>CC</sub> = 4.5		0.4		0.4		0.4	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -4.0mA, V <sub>CC</sub> = 4.5	2.4		2.4		2.4		V

NOTE: DC test conditions: V<sub>IH</sub> = V<sub>CC</sub> - 0.3V, V<sub>IL</sub> = 0.3V

**FIG. 4**  
**AC TEST CIRCUIT**



**AC TEST CONDITIONS**

Parameter	Typ	Unit
Input Pulse Levels	V <sub>IL</sub> = 0, V <sub>IH</sub> = 3.0	V
Input Rise and Fall	5	nS
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

**NOTES:**

- V<sub>2</sub> is programmable from -2V to +7V.
- I<sub>OL</sub> & I<sub>OH</sub> programmable from 0 to 16mA.
- Tester Impedance Z<sub>0</sub> = 75 Ω
- V<sub>2</sub> is typically the midpoint of V<sub>IH</sub> and V<sub>OL</sub>.
- I<sub>IL</sub> & I<sub>OH</sub> are adjusted to simulate a typical resistive load circuit.
- ATE tester includes jig capacitance.



**AC CHARACTERISTICS**  
(V<sub>CC</sub> = 5.0V, V<sub>SS</sub> = 0V, T<sub>A</sub> = -55°C to +125°C)

Parameter	Symbol	-17		-20		-25		-35		-45		-55		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
<b>Read Cycle</b>														
Read Cycle Time	t <sub>RC</sub>	17		20		25		35		45		55		nS
Address Access Time	t <sub>AA</sub>		17		20		25		35		45		55	nS
Output Hold from Address Change	t <sub>OH</sub>	5		5		5		5		5		5		nS
Chip Select Access Time	t <sub>ACS</sub>		17		20		25		35		45		55	nS
Output Enable to Output Valid	t <sub>OE</sub>		9		10		12		25		35		45	nS
Chip Select to Output in Low Z	t <sub>CLZ</sub> <sup>1</sup>	5		5		5		5		5		5		nS
Output Enable to Output in Low Z	t <sub>OLZ</sub> <sup>1</sup>	5		5		5		5		5		5		nS
Chip Disable to Output in High Z	t <sub>CHZ</sub> <sup>1</sup>		10		10		12		15		15		15	nS
Output Disable to Output in High Z	t <sub>OHZ</sub> <sup>1</sup>		10		10		12		15		15		15	nS

1. This parameter is guaranteed by design but not tested.

**AC CHARACTERISTICS**  
(V<sub>CC</sub> = 5.0V, V<sub>SS</sub> = 0V, T<sub>A</sub> = -55°C to +125°C)

Parameter	Symbol	-17		-20		-25		-35		-45		-55		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
<b>Write Cycle</b>														
Write Cycle Time	t <sub>WC</sub>	17		20		25		35		45		55		nS
Chip Select to End of Write	t <sub>CW</sub>	13		15		20		25		30		45		nS
Address Valid to End of Write	t <sub>AW</sub>	13		15		20		25		30		45		nS
Data Valid to End of Write	t <sub>DW</sub>	9		10		15		20		25		40		nS
Write Pulse Width	t <sub>WP</sub>	13		15		20		25		30		45		nS
Address Setup Time	t <sub>AS</sub>	0		0		0		0		0		0		nS
Address Hold Time	t <sub>AH</sub>	0		0		0		0		0		0		nS
Output Active from End of Write	t <sub>OW</sub> <sup>1</sup>	5		5		5		5		5		5		nS
Write Enable to Output in High Z	t <sub>WHZ</sub> <sup>1</sup>		10		12		15		20		25		25	nS
Data Hold Time	t <sub>DH</sub>	0		0		0		0		0		0		nS

1. This parameter is guaranteed by design but not tested.



FIG. 5  
TIMING WAVEFORM - READ CYCLE

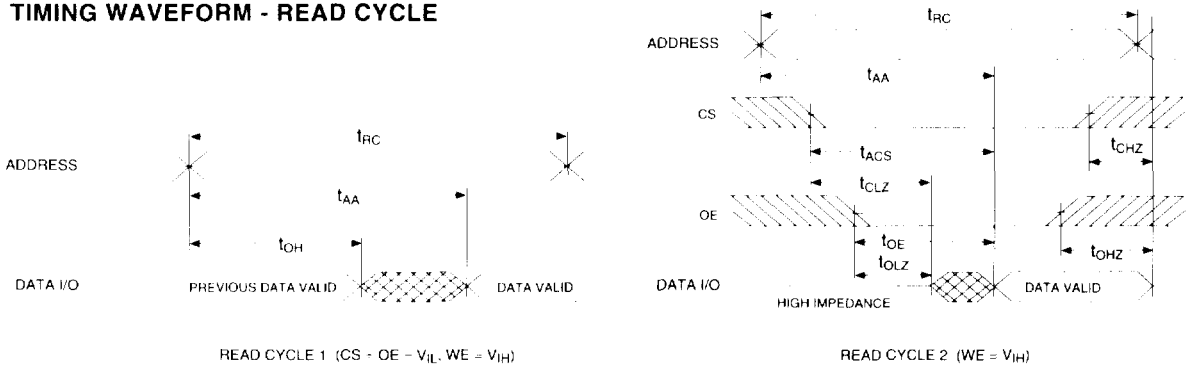


FIG. 6  
WRITE CYCLE - WE CONTROLLED

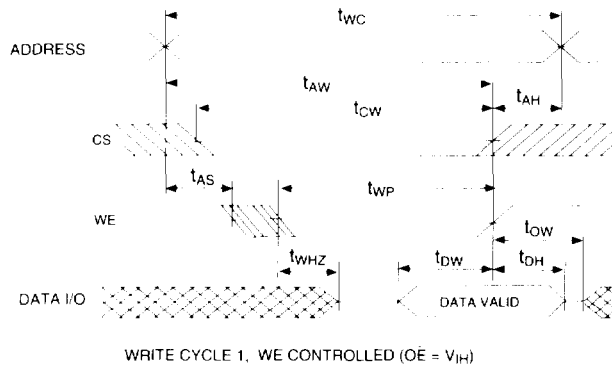
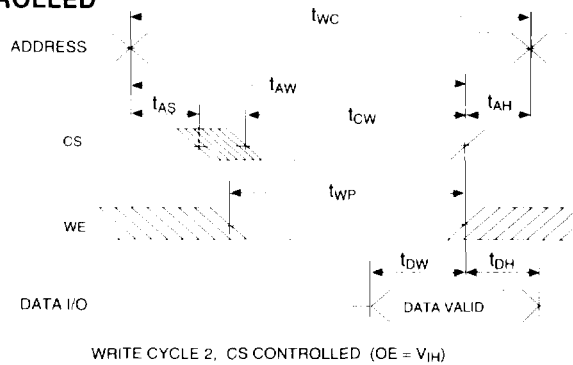


FIG. 7  
WRITE CYCLE - CS CONTROLLED





ORDERING INFORMATION

W M S 128K8 - XXX X X X

SPECIAL PROCESSING:

E = Epitaxial Layer

DEVICE GRADE:

Q = MIL-STD-883 Compliant

M = Military Screened -55°C to +125°C

I = Industrial -40°C to +85°C

C = Commercial 0°C to +70°C

PACKAGE:

DJ = Ceramic SOJ (Package 100)

F = Ceramic Flat Pack (Package 200)

C = Ceramic .600" DIP (Package 300)

ACCESS TIME in nS

ORGANIZATION, 128K x 8

SRAM

MONOLITHIC

WHITE MICROELECTRONICS

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